MAU2111

Silicon epitaxial planar type

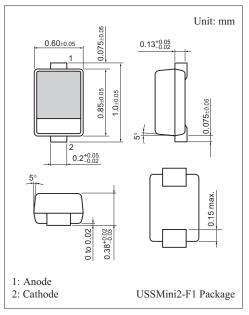
For high speed switching circuits

Features

- Optimum for high-density mounting
- Short reverse recovery time t_{rr}
- \bullet Small terminal capacitance C_t

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Reverse voltage	V _R	80	V	
Maximum peak reverse voltage	V _{RM}	80	V	
Forward current	$I_{\rm F}$	100	mA	
Forward current (Average)	I _{FM}	225	mA	
Non-repetitive peak forward surge current *	I _{FSM}	500	mA	
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



Marking Symbol: 11

Note) *: t = 1 s

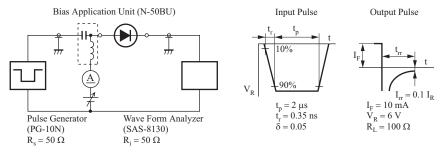
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward current	V _F	$I_F = 100 \text{ mA}$		0.95	1.2	V
Reverse voltage	V _R	$I_R = 100 \ \mu A$	80			V
Reverse current	I _R	$V_R = 75 V$			100	nA
Terminal capacitance	Ct	$V_{R} = 0, f = 1 MHz$		0.6	2	pF
Reverse recovery time *	t _{rr}	$\begin{split} I_{F} &= 10 \text{ mA}, V_{R} = 6 \text{ V}, I_{rr} = 0.1 \text{ I}_{R} , \\ R_{L} &= 100 \Omega \end{split}$			3.0	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

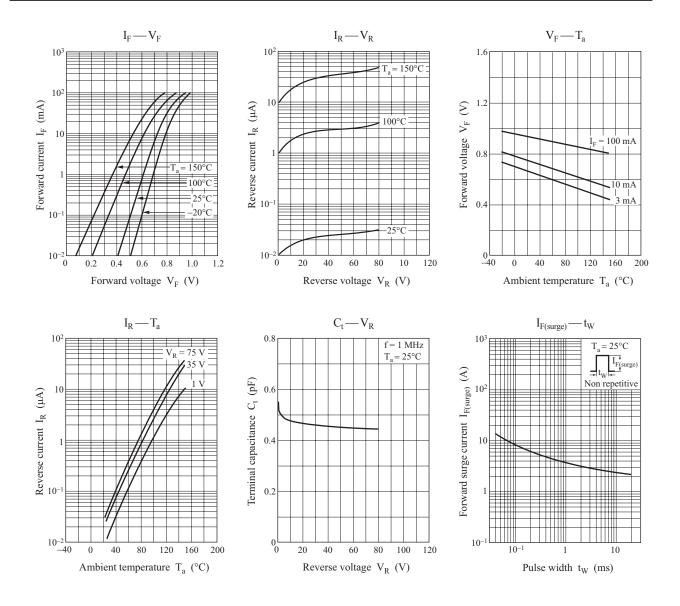
2. Absolute frequency of input and output is 100 MHz.

3. *: t_{rr} measurement circuit



MAU2111

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SKF00070AED

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